

ABSTRACT
CURABLE RESIN COMPOSITION

Provided is a curable resin composition which can provide a cured article having a low dielectric constant and a low dielectric tangent, and can also provide a
5 cured article having excellent moldability at ordinary press-molding temperatures, excellent heat resistance and excellent adhesion properties. The present invention provides a curable resin composition containing a polyphenylene ether, wherein the average number of
10 phenolic hydroxy groups is 0.3 or more per molecule of the polyphenylene ether, the resin flow amount of the curable resin composition upon curing is 0.3 to 15% inclusive, and a cured article having a dielectric tangent of 0.005 or less at 1 GHz and a glass transition
15 temperature of 170°C or higher can be produced.